

Phase-Aligned Clock Multiplier

Features

- 10 MHz to 166.67 MHz output operating range
- Four-multiplier configuration
- Single PLL architecture
- Phase aligned outputs
- Low jitter, high accuracy outputs
- Output enable pin
- 3.3 V operation
- 5 V tolerant input
- Internal loop filter
- 8-pin 150-mil small-outline integrated circuit (SOIC) package
- Commercial temperature

Functional Description

The CY2300 is a four output 3.3 V phase-aligned system clock designed to distribute high-speed clocks in PC, workstation, datacom, telecom, and other high-performance applications.

The part allows the user to obtain 1/2x, 1x, 1x and 2x REFIN output frequencies on respective output pins.

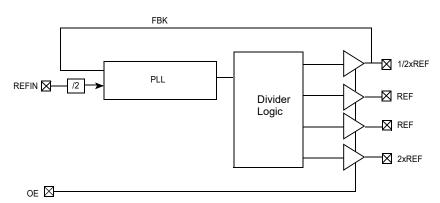
The part has an on-chip PLL which locks to an input clock presented on the REFIN pin. The input-to-output skew is guaranteed to be less than ± 200 ps, and output-to-output skew is guaranteed to be less than 200 ps.

Multiple CY2300 devices can accept the same input clock and distribute it in a system. In this case, the skew between the outputs of two devices is guaranteed to be less than 400 ps.

The CY2300 is available in commercial temperature range.

For a complete list of related documentation, click here.

Logic Block Diagram





Contents

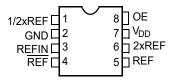
Pinouts	3
Pin Definitions	3
Maximum Ratings	4
Operating Conditions	4
Electrical Characteristics	4
Thermal Resistance	4
Test Circuits	5
Switching Characteristics	5
Switching Waveforms	6
Ordering Information	
Ordering Code Definitions	
Package Drawing and Dimensions	
Reference Documents	
Acronyms	9

Document Conventions	9
Units of Measure	9
Errata	10
Part Numbers Affected	10
CY2300 Errata Summary	10
CY2300 Qualification Status of fixed silicon	10
Document History Page	12
Sales, Solutions, and Legal Information	
Worldwide Sales and Design Support	13
Products	
PSoC®Solutions	13
Cypress Developer Community	13
Technical Support	13



Pinouts

Figure 1. 8-pin SOIC pinout (Top View)



Pin Definitions

Pin	Signal ^[1]	Description
1	1/2xREF	Clock output, 1/2x reference
2	GND	Ground
3	REFIN	Input reference frequency, 5 V tolerant input
4	REF	Clock output reference
5	REF	Clock output reference
6	2xREF	Clock output, 2x reference
7	V_{DD}	3.3 V Supply
8	OE	Output enable (weak pull-up)

Note
1. Weak pull-down on all outputs.



Maximum Ratings

Supply voltage to ground potential-0.5 V to +7.0 V DC input voltage (except ref)-0.5 V to V_{DD} + 0.5 V DC input voltage REF-0.5 V to 7 V

Storage temperature65 °C to +150 °C
Junction temperature
Static discharge voltage (per MIL-STD-883, method 3015)> 2000 V

Operating Conditions

Parameter	Description	Min	Max	Unit
V_{DD}	Supply voltage	3.0	3.6	V
T _A	Operating temperature (ambient temperature)	0	70	°C
C _L	Load capacitance, 10 MHz < F _{OUT} < 133.33 MHz	_	18	pF
	Load capacitance,133.33 MHz < F _{OUT} < 166.67 MHz	_	12	pF
C _{IN}	Input capacitance	_	7	pF
t _{PU}	Power-up time for all V_{DD} 's to reach minimum specified voltage (power ramps must be monotonic)	0.05	50	ms

Electrical Characteristics

Parameter	Description	Test Conditions	Min	Max	Unit
V _{IL}	Input LOW voltage		_	0.8	V
V _{IH}	Input HIGH voltage		2.0	-	V
I _{IL}	Input LOW current	V _{IN} = 0 V	_	100	μΑ
I _{IH}	Input HIGH current	$V_{IN} = V_{DD}$	_	50	μΑ
V_{OL}	Output LOW voltage [2]	I _{OL} = 8 mA	_	0.4	V
V _{OH}	Output HIGH voltage [2]	I _{OH} = –8 mA	2.4	-	V
I_{DD}	Supply current	Unloaded outputs, REFIN = 66 MHz	_	45	mA
		Unloaded outputs, REFIN = 33 MHz	_	32	mA
		Unloaded outputs, REFIN = 20 MHz	_	18	mA

Thermal Resistance

Parameter [3]	Description	Test Conditions	8-pin SOIC	Unit
θ_{JA}	,	Test conditions follow standard test methods and procedures for measuring thermal impedance, in		°C/W
00	Thermal resistance (junction to case)	accordance with EIA/JESD51.	54	°C/W

Notes

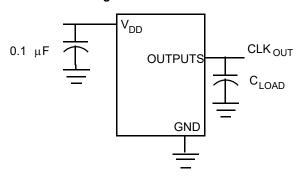
- Parameter is guaranteed by design and characterization. It is not 100% tested in production.
 These parameters are guaranteed by design and are not tested.

Document Number: 38-07252 Rev. *J



Test Circuits

Figure 2. Test Circuit #1



Switching Characteristics

Parameter	Description	Test Conditions	Min	Тур	Max	Unit
1/t ₁	Output frequency	18 pF load	10	-	133.33	MHz
		12 pF load	-	-	166.67	MHz
	Duty cycle ^[4] = $t_2 \div t_1$	Measured at V _{DD} /2	40	50	60	%
t ₃	Rise time ^[4]	Measured between 0.8 V and 2.0 V	_	-	1.20	ns
t ₄	Fall time ^[4]	Measured between 0.8 V and 2.0 V	-	-	1.20	ns
t ₅	Output to output skew on rising edges ^[4]	All outputs equally loaded Measured at V _{DD} /2	-	_	200	ps
t ₆	Delay, REFIN rising edge to output rising edge ^[4]	Measured at V _{DD} /2 from REFIN to any output	_	_	±200	ps
t ₇	Device to device skew ^[4]	Measured at V _{DD} /2 on the 1/2xREF pin of devices (pin 1)	_	_	400	ps
t _J	Period jitter ^[4]	Measured at Fout = 133.33 MHz, loaded outputs, 18 pF load	-	-	±175	ps
t _{LOCK}	PLL lock time ^[4]	Stable power supply, valid clocks presented on REFIN	_	_	1.0	ms

Note

Document Number: 38-07252 Rev. *J

^{4.} All parameters are specified with equally loaded outputs.



Switching Waveforms

Figure 3. Duty Cycle Timing

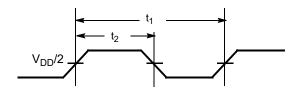


Figure 4. All Outputs Rise/Fall Time

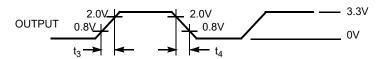


Figure 5. Output to Output Skew

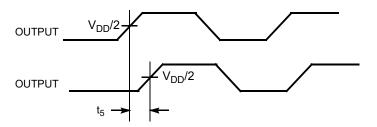


Figure 6. Input to Output Propagation Delay

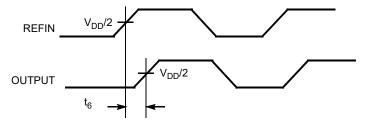
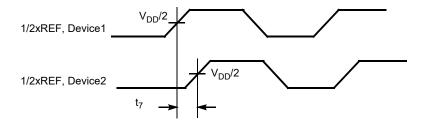


Figure 7. Device to Device Skew

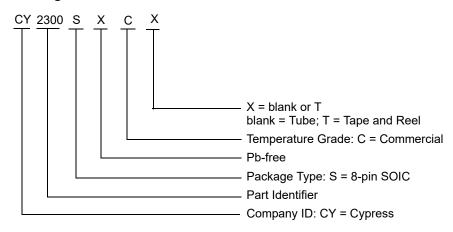




Ordering Information

Ordering Code	Package Type	Operating Range	
Pb-free			
CY2300SXC	8-pin SOIC	Commercial (0 °C to 70 °C)	
CY2300SXCT	8-pin SOIC - Tape and Reel	Commercial (0 °C to 70 °C)	

Ordering Code Definitions



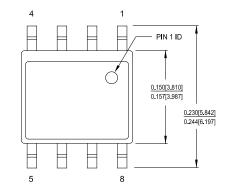


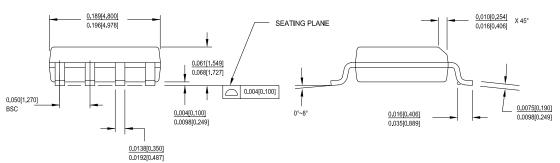
Package Drawing and Dimensions

Figure 8. 8-pin SOIC (150 Mils) Package Outline, 51-85066

- 1. DIMENSIONS IN INCHES[MM] MIN.
- PIN 1 ID IS OPTIONAL,
 ROUND ON SINGLE LEADFRAME
 RECTANGULAR ON MATRIX LEADFRAME
- 3. REFERENCE JEDEC MS-012
- 4. PACKAGE WEIGHT 0.07gms

PART #		
S08.15	STANDARD PKG	
SZ08.15	LEAD FREE PKG	
SW8.15	LEAD FREE PKG	





51-85066 *I



Reference Documents

Reference documents are available through your local Cypress sales representative. You can also direct your requests to tsbusdev@cypress.com.

Document Number	Document Title	Description
NA	NA	NA

Acronyms

Acronym	Description	
FBK	Feedback	
OE	Output Enable	
PLL	Phase Locked Loop	
REFIN	Reference Input	

Document Conventions

Units of Measure

Symbol	Unit of Measure		
°C	degree Celsius		
Hz	hertz		
kHz	kilohertz		
MHz	megahertz		
μA	microampere		
μF	microfarad		
μs	microsecond		
μV	microvolt		
mA	milliampere		
mm	millimeter		
ms	millisecond		
mV	millivolt		
ns	nanosecond		
pA	picoampere		
pF	picofarad		
ps	picosecond		
V	volt		



Errata

This section describes the errors, workaround solution and silicon design fixes for Cypress zero delay clock buffers belonging to the families CY2300. Details include errata trigger conditions, scope of impact, available workaround and silicon revision applicability. Contact your local Cypress Sales Representative if you have questions.

Part Numbers Affected

Part Number	Device Characteristics
CY2300SXC	All Variants
CY2300SXCT	All Variants

CY2300 Errata Summary

Items	Part Number	Fix Status
Start up lock time issue [CY2300]	All	Silicon fixed. New silicon available from WW 10 of 2013

CY2300 Qualification Status of fixed silicon

Product Status: In production

Qualification report last updated on 11/27/2012

http://www.cypress.com/?rID=72595

1. Start up lock time issue

■ Problem Definition

Output of CY2300 fails to locks within 1 ms upon power up (as per datasheet spec).

■ Parameters Affected

PLL lock time (t_{LOCK})

■ Trigger Condition(S)

Start up

■ Scope of Impact

It can impact the performance of system and its throughput.

■ Workaround

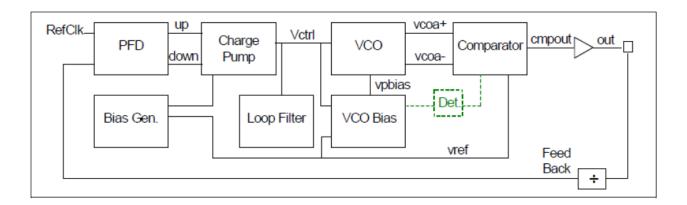
Apply reference input (RefClk) before power up (VDD). If RefClk is applied after power up, noise gets coupled on the output and propagates back to the PLL causing it to take higher time to acquire lock. If reference input is present during power up, noise will not propagate to the PLL and device will start up normally without problems.

■ Fix Status

This issue is due to design marginality. Two minor design modifications have been made to address this problem.

- a. Addition of VCO bias detector block as shown in the following figure keeps comparator power down till VCO bias is present and thereby eliminating the propagation of noise to feedback.
- b. Bias generator enhancement for successful initialization.







Document History Page

Rev.	ECN	Orig. of Change	Submission Date	Description of Change	
**	110517	SZV	01/07/2002	Changed from spec number 38-01039 to spec number 38-07252.	
*A	121854	RBI	12/14/2002	Updated Operating Conditions: Added t _{PU} parameter and its details.	
*B	246829	RGL	08/02/2004	Updated Ordering Information: Updated part numbers (Added Lead Free Devices).	
*C	2568533	AESA	09/23/2008	Removed Selector Guide. Removed Operating Conditions (for CY2300SI Industrial Temperature Devices). Removed Electrical Characteristics (for CY2300SI Industrial Temperature Devices). Removed Switching Characteristics (for CY2300SI Industrial Temperature Devices). Updated Ordering Information: Updated part numbers (Removed part numbers CY2300SC, CY2300SI, CY2300SI, CY2300SXI and CY2300SXIT). Updated to new template.	
*D	3026183	BASH	09/01/2010	Removed Benefits. Updated Operating Conditions: Updated details in "Description" column corresponding to C _L parameter (Added lower limit of 10 MHz for 18pF load capacitance). Updated Ordering Information: No change in part numbers. Added Ordering Code Definitions. Added Reference Documents, Acronyms and Units of Measure.	
*E	4126294	CINM	11/25/2013	Updated Package Drawing and Dimensions: spec 51-85066 – Changed revision from *D to *F. Added Errata. Updated to new template. Completing Sunset Review.	
*F	4325140	CINM	03/28/2014	Updated Errata.	
*G	4578443	TAVA	11/25/2014	Updated Functional Description: Added "For a complete list of related documentation, click here." at the er	
*H	5240894	PSR	04/25/2016	Updated Features: Added "10 MHz to 166.67 MHz output operating range". Added Thermal Resistance. Updated Package Drawing and Dimensions: spec 51-85066 – Changed revision from *F to *H. Updated to new template.	
*	5542709	TAVA	12/05/2016	Updated to new template. Completing Sunset Review.	
*J	6010798	PAWK	01/02/2018	Updated Package Drawing and Dimensions: spec 51-85066 – Changed revision from *H to *I. Updated to new template.	



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Document Number: 38-07252 Rev. *J Revised January 2, 2018 Page 13 of 13